

MOSFET – Power, P-Channel, SOT-23

-20 V, -1 A

NTR1P02, NVR1P02

Features

- Ultra Low On-Resistance Provides Higher Efficiency and Extends Battery Life
 $R_{DS(on)} = 0.180 \Omega$, $V_{GS} = -10 \text{ V}$
 $R_{DS(on)} = 0.280 \Omega$, $V_{GS} = -4.5 \text{ V}$
- Power Management in Portable and Battery-Powered Products
- Miniature SOT-23 Surface Mount Package Saves Board Space
- Mounting Information for SOT-23 Package Provided
- NVR Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Applications

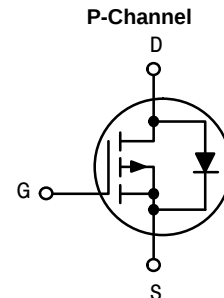
- DC-DC Converters
- Computers
- Printers
- PCMCIA Cards
- Cellular and Cordless Telephones

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

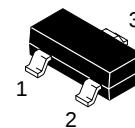
Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	-20	V
Gate-to-Source Voltage – Continuous	V_{GS}	± 20	V
Drain Current – Continuous @ $T_A = 25^\circ\text{C}$ – Pulsed Drain Current ($t_p \leq 1 \mu\text{s}$)	I_D I_{DM}	-1.0 -2.67	A
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	400	mW
Operating and Storage Temperature Range	T_J, T_{stg}	-55 to 150	$^\circ\text{C}$
Thermal Resistance; Junction-to-Ambient	$R_{\theta JA}$	300	$^\circ\text{C/W}$
Maximum Lead Temperature for Soldering Purposes, (1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

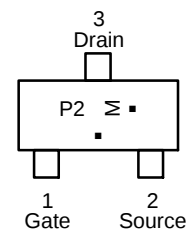
$V_{(BR)DSS}$	$R_{DS(on)}$ TYP	I_D MAX
-20 V	148 m Ω @ -10 V	-1.0 A



MARKING DIAGRAM/ PIN ASSIGNMENT



SOT-23
CASE 318
STYLE 21



P2 = Specific Device Code
M = Date Code
▪ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTR1P02T1G	SOT-23 (Pb-Free)	3000 / Tape & Reel
NVR1P02T1G	SOT-23 (Pb-Free)	3000 / Tape & Reel

DISCONTINUED (Note 1)

NTR1P02T3G	SOT-23 (Pb-Free)	10000 / Tape & Reel
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† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

- DISCONTINUED:** This device is not recommended for new design. Please contact your onsemi representative for information. The most current information on this device may be available on [www.onsemi.com](#).

NTR1P02, NVR1P02

ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage ($V_{GS} = 0\text{ V}$, $I_D = -10\text{ }\mu\text{A}$) (Positive Temperature Coefficient)	$V_{(BR)DSS}$	-20	32		V mV/ $^{\circ}\text{C}$
Zero Gate Voltage Drain Current ($V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 25\text{ }^{\circ}\text{C}$) ($V_{DS} = -20\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 150\text{ }^{\circ}\text{C}$)	I_{DSS}			-1.0 -10	μA
Gate-Body Leakage Current ($V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$)	I_{GSS}			± 100	nA

ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = -250\text{ }\mu\text{A}$) (Negative Temperature Coefficient)	$V_{GS(th)}$	-1.1	-1.9 -4.0	-2.3	V mV/ $^{\circ}\text{C}$
Static Drain-to-Source On-State Resistance ($V_{GS} = -10\text{ V}$, $I_D = -1.5\text{ A}$) ($V_{GS} = -4.5\text{ V}$, $I_D = -0.75\text{ A}$)	$R_{DS(on)}$		0.148 0.235	0.180 0.280	Ω

DYNAMIC CHARACTERISTICS

Input Capacitance ($V_{DS} = -5\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$)	C_{iss}		165		pF
Output Capacitance ($V_{DS} = -5\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$)	C_{oss}		110		
Reverse Transfer Capacitance ($V_{DS} = -5\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$)	C_{rss}		35		

SWITCHING CHARACTERISTICS (Note 3)

Turn-On Delay Time ($V_{DD} = -15\text{ V}$, $I_D = -1\text{ A}$, $V_{GS} = -5\text{ V}$, $R_G = 2.5\text{ }\Omega$)	$t_{d(on)}$		7.0		ns
Rise Time ($V_{DD} = -15\text{ V}$, $I_D = -1\text{ A}$, $V_{GS} = -5\text{ V}$, $R_G = 2.5\text{ }\Omega$)	t_r		9.0		
Turn-Off Delay Time ($V_{DD} = -15\text{ V}$, $I_D = -1\text{ A}$, $V_{GS} = -5\text{ V}$, $R_G = 2.5\text{ }\Omega$)	$t_{d(off)}$		9.0		
Fall Time ($V_{DD} = -15\text{ V}$, $I_D = -1\text{ A}$, $V_{GS} = -5\text{ V}$, $R_G = 2.5\text{ }\Omega$)	t_f		3.0		
Total Gate Charge ($V_{DS} = -15\text{ V}$, $V_{GS} = -5\text{ V}$, $I_D = -0.8\text{ A}$)	Q_{tot}		2.5		nC
Gate-Source Charge ($V_{DS} = -15\text{ V}$, $V_{GS} = -5\text{ V}$, $I_D = -0.8\text{ A}$)	Q_{gs}		0.75		
Gate-Drain Charge ($V_{DS} = -15\text{ V}$, $V_{GS} = -5\text{ V}$, $I_D = -0.8\text{ A}$)	Q_{gd}		1.0		

BODY-DRAIN DIODE RATINGS (Note 2)

Diode Forward On-Voltage (Note 3) ($I_S = -0.6\text{ A}$, $V_{GS} = 0\text{ V}$) ($I_S = -0.6\text{ A}$, $V_{GS} = 0\text{ V}$, $T_J = 150\text{ }^{\circ}\text{C}$)	V_{SD}		-0.8 -0.6	-1.0	V
Reverse Recovery Time ($I_S = -1\text{ A}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$, $V_{GS} = 0\text{ V}$)	t_{rr}		13.5		ns
	t_a		10.5		
	t_b		3.0		
Reverse Recovery Stored Charge ($I_S = -1\text{ A}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$, $V_{GS} = 0\text{ V}$)	Q_{RR}		0.008		μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width $\leq 300\text{ }\mu\text{s}$, Duty Cycle $\leq 2\%$.

3. Switching characteristics are independent of operating junction temperature.



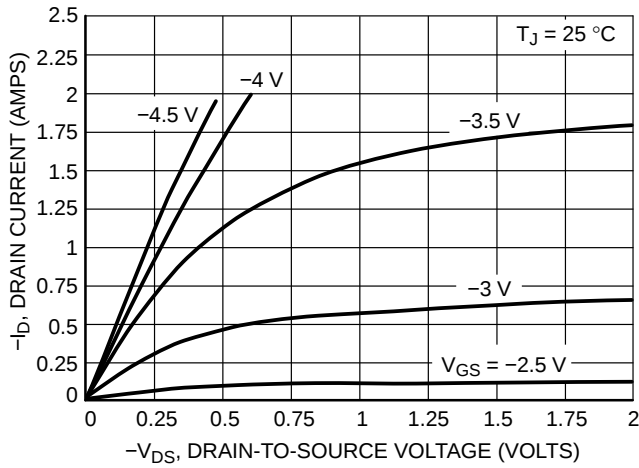


Figure 1. On-Region Characteristics

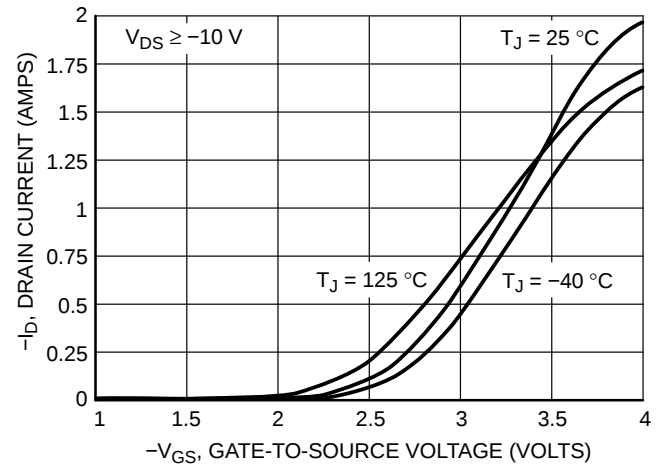


Figure 2. Transfer Characteristics

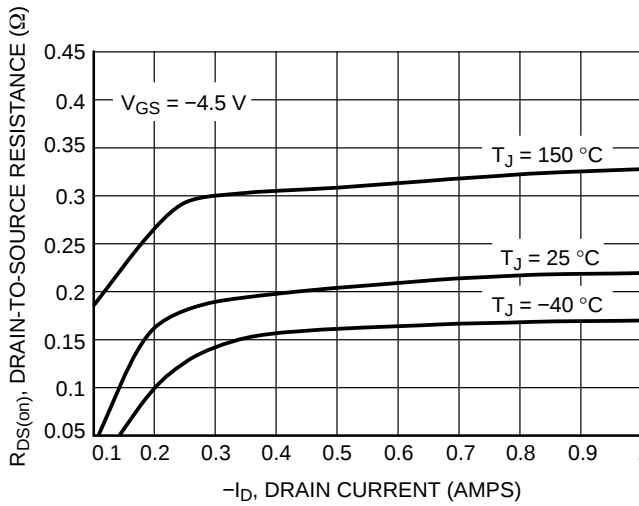


Figure 3. On-Resistance versus Drain Current and Temperature

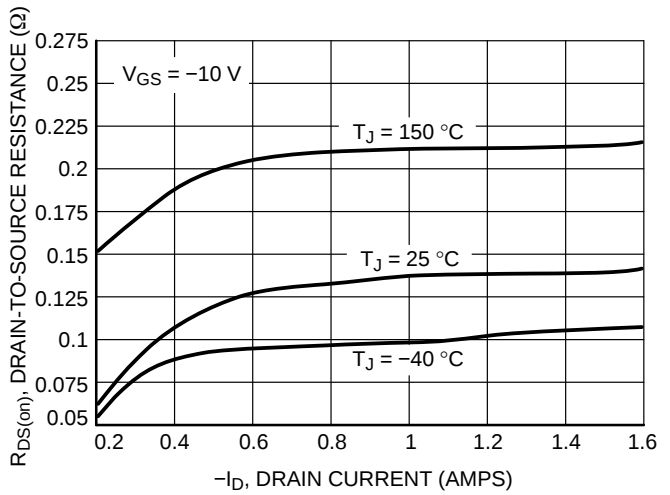


Figure 4. On-Resistance versus Drain Current and Temperature

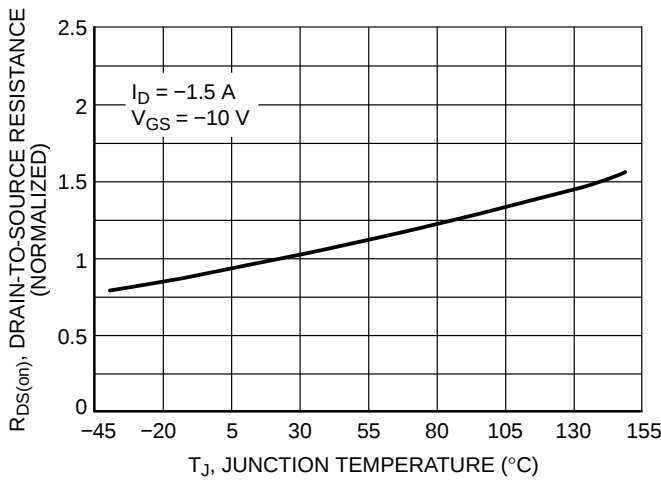


Figure 5. On-Resistance Variation with Temperature

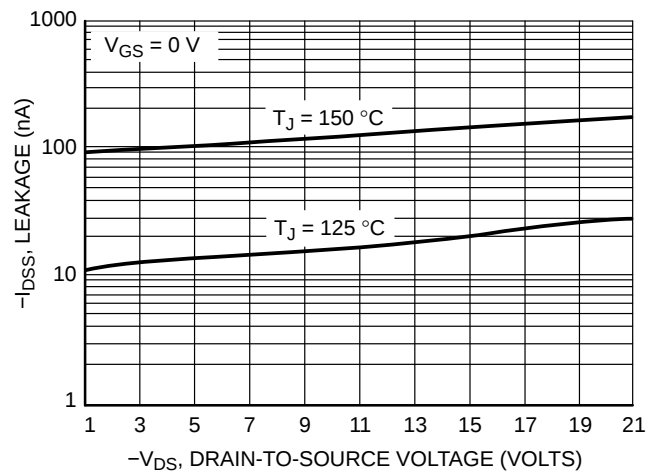
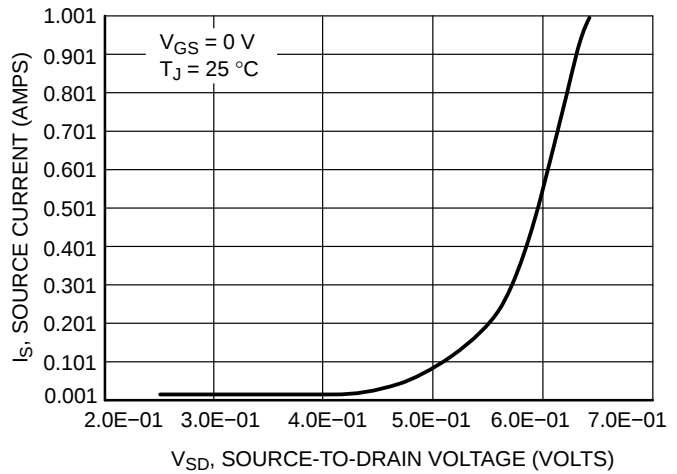
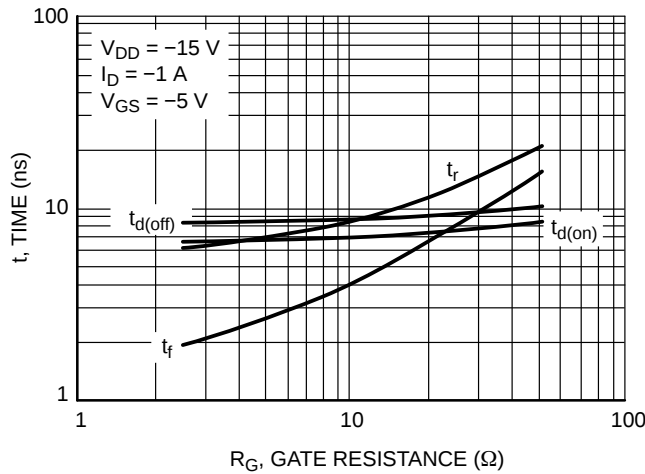
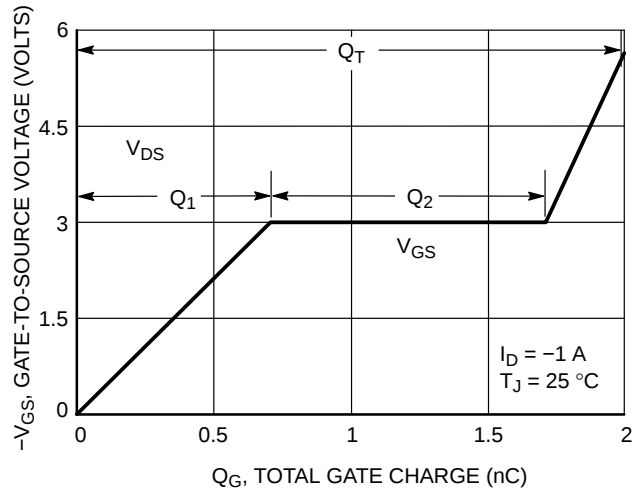
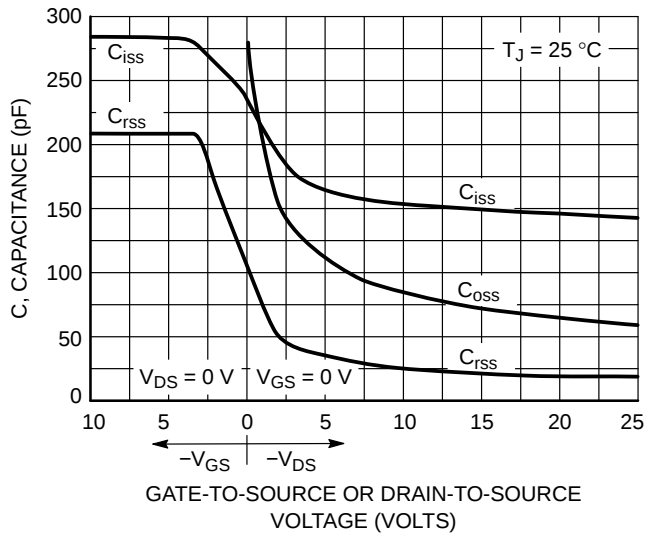


Figure 6. Drain-to-Source Leakage Current versus Voltage



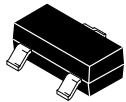
NTR1P02, NVR1P02

REVISION HISTORY

Revision	Description of Changes	Date
9	Rebranded the document to onsemi format. NTR1P02T3G OPN marked as Discontinued.	2/5/2026

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

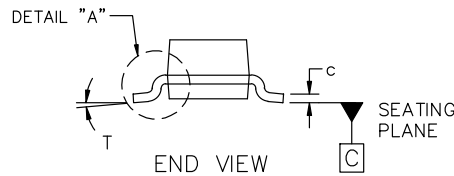
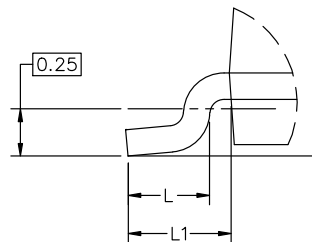
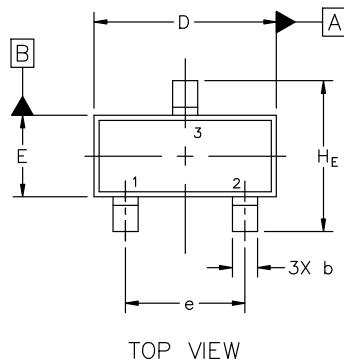




SCALE 4:1

SOT-23 (TO-236) 2.90x1.30x1.00 1.90P
CASE 318
ISSUE AU

DATE 14 AUG 2024



MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.89	1.00	1.11
A1	0.01	0.06	0.10
b	0.37	0.44	0.50
c	0.08	0.14	0.20
D	2.80	2.90	3.04
E	1.20	1.30	1.40
e	1.78	1.90	2.04
L	0.30	0.43	0.55
L1	0.35	0.54	0.69
HE	2.10	2.40	2.64
T	0°	---	10°

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE		
STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE	STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE	STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE
STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE	STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE	STYLE 19: PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE	STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE
STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN	STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT	STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE	STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE	STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE	STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE				

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